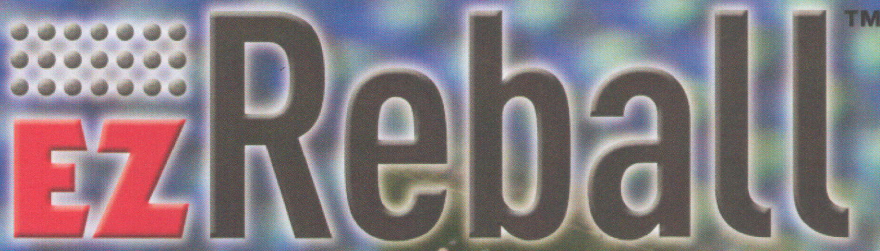
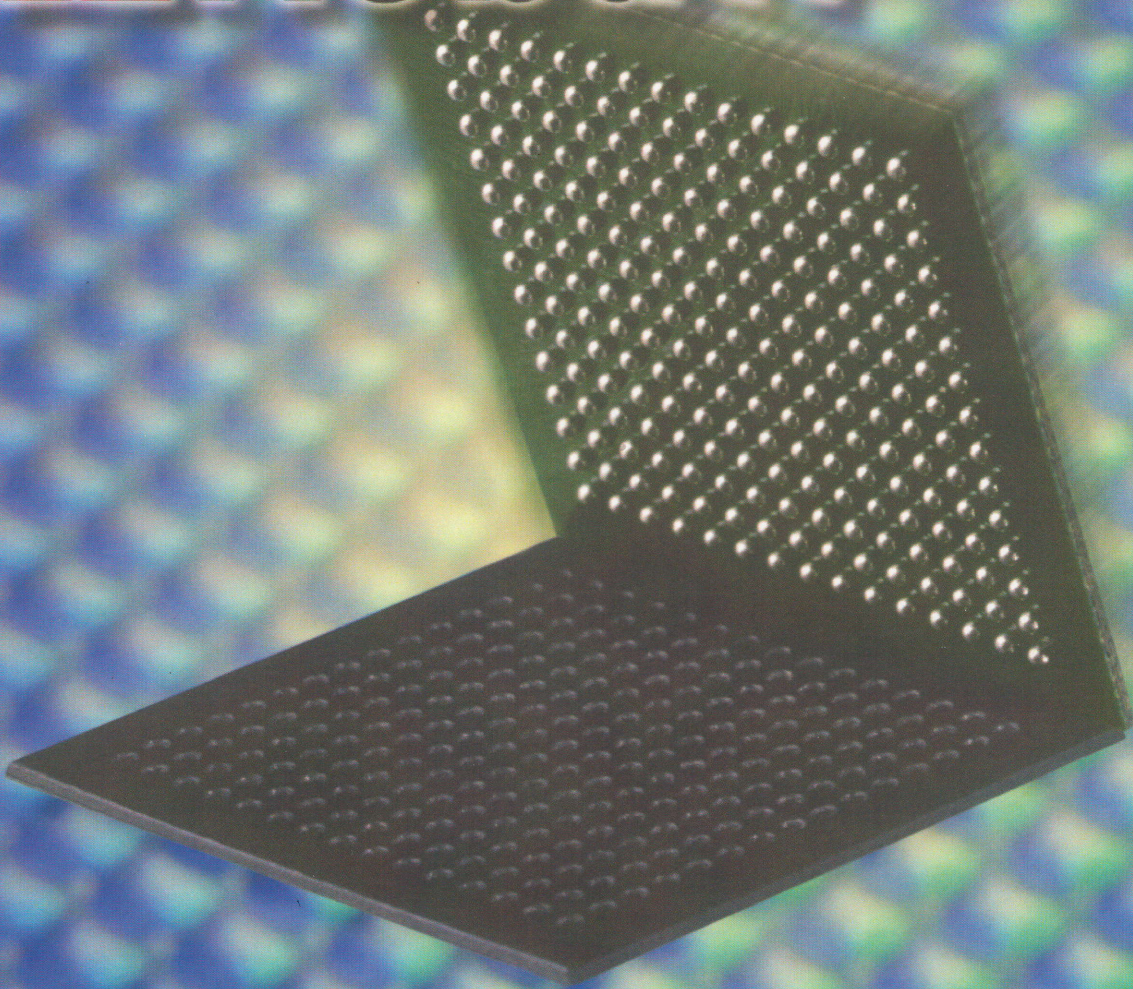


BGA Reballing

FAST, SIMPLE, and RELIABLE

**EZReball**TM



EZReballTM — An easy method for reballing BGAs

EZReballTM patent pending BEST Inc.

BEST

3603 Edison Place • Rolling Meadows, IL 60008
v: 847.797.9250 • f: 847.797.9255

Your **BEST** choice in Solder Rework/Repair, Solder Training and Soldering Tools

www.solder.net

EZReball™

The EZReball™ Process Difference... Simple and Fast!

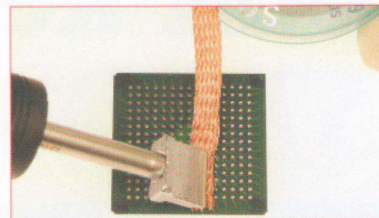
Are you tired of the existing reballing methods being in the hands of process experts due to the complexities and the dexterity required? Do you desire to have a faster reballing method? The new **BEST EZReball™** process is an answer to your reballing problems. This unique method simplifies the reballing process allowing for better yields and faster reballing times.

The simple nature of the **EZReball™** reballing process allows even the beginning repair technician to reliably and quickly re-add balls to a package. Alignment is simple with the edges of the preform being "squared up" with the sides of the package thereby eliminating the need to buy custom fixtures or frames. The adhesive is engineered such that the balls are firmly held in place until after reflow thereby reducing the problem of missing solder balls found in other techniques. After the device has been reflowed, the preform is simply peeled off, eliminating the time required in cleaning off residual paper used in other methods.

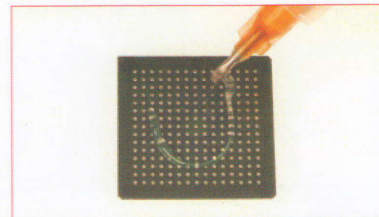
The **EZReball™** preforms are packaged and delivered to you the way you want. Preforms are custom made to your exact alloy and device array requirements without expensive tooling. They are also packaged such that developers and those building PCB prototypes can use them in quantities which more closely match their needs.

These reballing preforms are a simple, reliable, and easy-to-use reballing tool. **EZReball™** preforms are manufactured to your exacting specifications from a specialty high temperature-rated film, which aligns the balls. The balls are aligned through these apertures and held in place using an engineered adhesive system. The preform is cut using a laser to your exacting device requirements. Solder balls are captured and retained by the preform and are aligned to the prepped device and reflowed. After reflow the preform is simply peeled away.

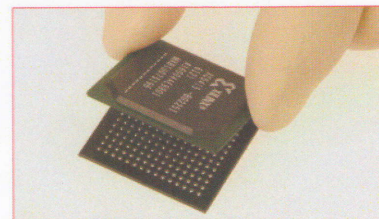
How the EZReball™ process works



Step 1 – Wick BGA and clean with alcohol



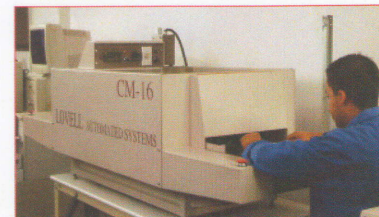
Step 2 – Apply thin layer of paste flux to BGA



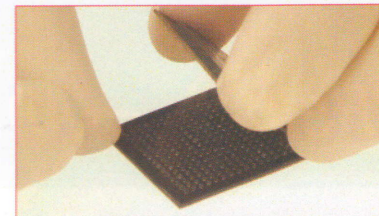
Step 3 – Place BGA on top of EZReball™ preform



Step 4 – Align BGA with EZReball™ preform



Step 5 – Reflow BGA using your own profile



Step 6 – Remove EZReball™ preform from BGA

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